



BRIDGE RECTIFIERS

Reverse Voltage - 50 to 1000 V

Forward Current - 8.0 A

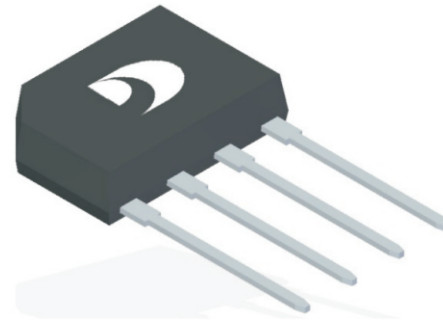
FEATURES

- Rating to 1000V PRV
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- The plastic material has UL flammability classification 94V#0

MECHANICAL DATA

- Polarity : As marked on body
- Weight : 0.05 ounces, 1.52 grams
- Mounting position : Any

KBP



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

CHARACTERISTICS	SYMBOL	KBP 8005	KBP 801	KBP 802	KBP 804	KBP 806	KBP 808	KBP 810	Units	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V	
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V	
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V	
Maximum Average Forward Rectified Current @ $T_C=100^{\circ}C$	$I_{(AV)}$					8.0 2.4				A
Peak Forward Surge Current 8.3ms single half sine-wave	I_{FSM}					150				A
Maximum Forward Voltage at 4.0A DC	V_F					1.0				V
Maximum DC Reverse Current at rated Blocking Voltage	I_R					5 500				μA
I^2t Rating for fusing (t=8.3ms)	I^2t					93				A^2S
Typical Junction Capacitance per element (Note 1)	C_j					60				pF
Typical thermal resistance (Unit mounted on 75mmx75mmx1.6mm Copper plate heat sink.)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$					15 6 8				$^{\circ}C/W$
Typical thermal resistance (without heat sink)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$					40 14 20				$^{\circ}C/W$
Operating Junction Temperature Range	T_j					-55 ~ +150				$^{\circ}C$
Storage Temperature Range	T_{stg}					-55 ~ +150				$^{\circ}C$

Note: (1) Measured at 1.0MHz and applied reverse voltage of 4.0V DC.



Fig.1 Forward Current Derating Curve

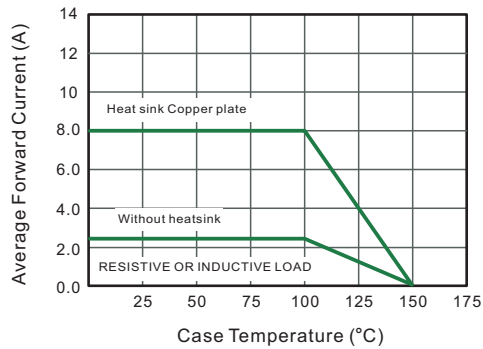


Fig.2 Typical Instaneous Reverse Characteristics

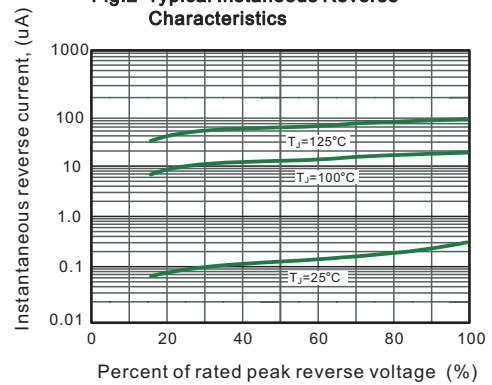


Fig.3 Typical Forward Characteristic

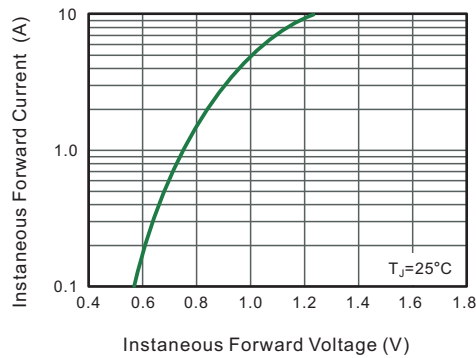


Fig.4 Typical Junction Capacitance

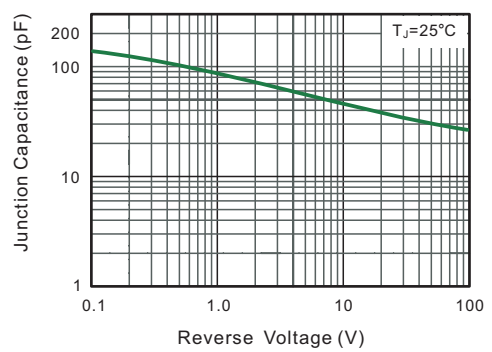


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

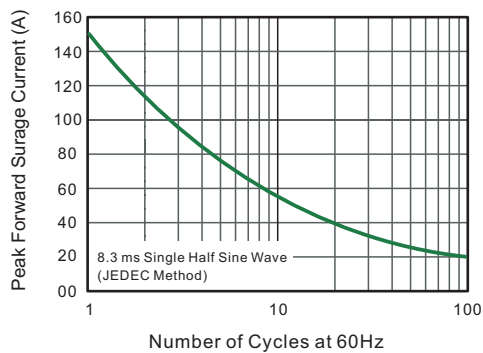
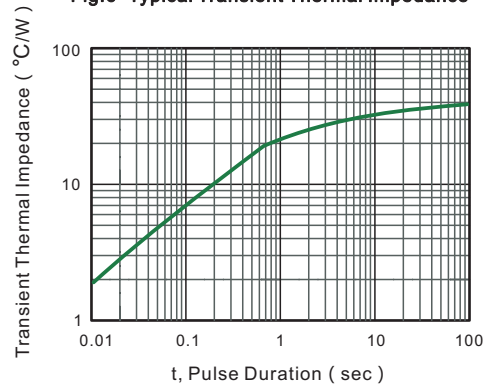
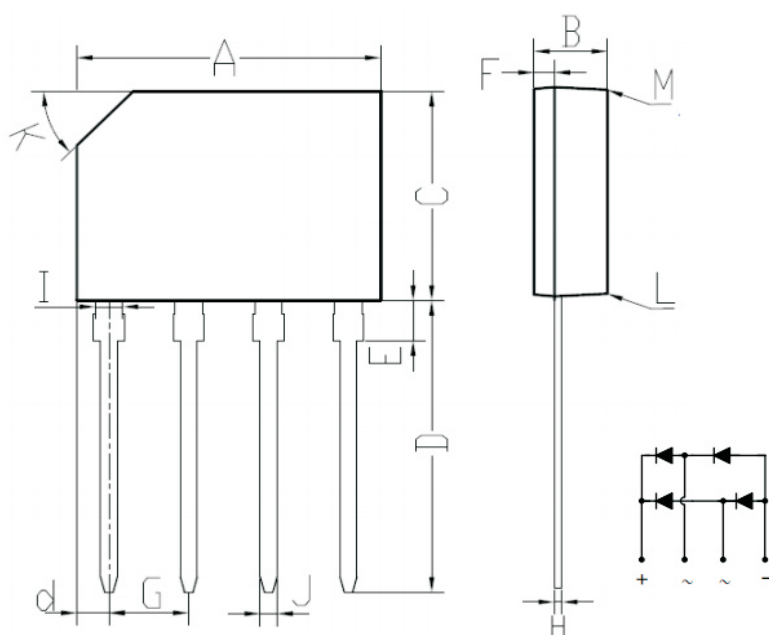


Fig.6- Typical Transient Thermal Impedance





KBP Package Outline Dimensions



KBP		
DIM.	MIN.	MAX.
A	14.25	14.75
B	3.35	3.65
C	10.20	10.60
D	14.25	14.73
d	1.40	1.70
E	1.80	2.20
F	0.80	1.10
G	3.56	4.06
H	0.35	0.55
I	1.22	1.42
J	0.76	0.86
K	2.7 x 45° (Typ)	
L	#	3°
M	#	2°
All Dimensions in millimeter		

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文件履历表

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